

PATENT APPLN. NO. 10/802,059  
RESPONSE UNDER 37 C.F.R. §1.111

**PATENT  
NON-FINAL**

**REMARKS**

The title of the invention has been amended substantially as proposed in the Action. The abstract of the disclosure has been amended to delete legal phraseology. Removal of objections to the specification is believed to be in order and is respectfully requested.

Claim 1 has been amended to include the limitations of claim 3. Claim 3 has been canceled.

Claims 1-3 are rejected under 35 U.S.C. §102(b) as being anticipated by Massengale et al. (U.S. Patent No. 5,686,521; hereinafter "Massengale").

The transport and storage carrier for semiconductor members including wafers of the present invention as claimed in amended claim 1 is characterized in that the carrier is molded from a resin composition comprising a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, where the carbon fibril is 3.5 to 75 nm in average diameter and 5 to 1000 in aspect ratio.

Massengale discloses a milled fiber reinforced polymer composition where the milled carbon fibers (MCF) have a diameter between 0.0007 and 0.0009 inches (column 3 to column 4). This

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range of diameter corresponds to 17.8 to 22.9  $\mu\text{m}$  and also to 17800 to 22900 nm.

Massengale fails to disclose or suggest a carrier for semiconductor members which is molded from a resin composition containing a synthetic resin and a carbon fibril admixed with the resin, where the carbon fibril is 3.5 to 75 nm in average diameter and is insufficient, therefore, to support anticipation under 35 U.S.C. § 102 or obviousness under 35 U.S.C. § 103(a).

Regarding a possible issue of obviousness, applicants note that Examples 1-3 of the present application show that moldings made from the composition according to the present invention (carbon fibril: HP 5 nm) have particularly excellent effects as compared to moldings made from the composition of Comparative Example 1 (carbon fiber: 10  $\mu\text{m}$  = 10000 nm). More specifically, the data of Table 1 show excellent surface resistivity and the data of Table 2 show excellent abrasion resistance for moldings according to the present invention and the data of Test Example 3 show a small evolution of gas at high temperatures for moldings according to the present invention.

Claim 2 is rejected under 35 U.S.C. §103(a) as being obvious over Massengale in view of Kinoshita et al. (U.S. Patent Appln. Pub. No. 2002/0139961; hereinafter "Kinoshita"). Claim 4 is

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rejected under 35 U.S.C. §103(a) as obvious over Massengale in view of Kubotera et al. (U.S. Patent No. 6,540,945; hereinafter "Kubotera").

Kinoshita and Kubotera fail to overcome the insufficiencies of Massengale and, more particularly, fail to disclose or suggest a carrier molded from a resin composition comprising a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, where the carbon fibril is 3.5 to 75 nm in average diameter and 5 to 1000 in aspect ratio.

For the above reasons the 35 U.S.C. § 102 and 35 U.S.C. § 103(a) rejections are improper and should be removed.

The foregoing is believed to be a complete and proper response to the Office Action dated July 5, 2005, and is believed to place this application in condition for allowance. If, however, minor issues remain that can be resolved by means of a telephone interview, the Examiner is respectfully requested to contact the undersigned attorney at the telephone number indicated below.

In the event that this paper is not considered to be timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to our Deposit Account No. 111833.

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In the event any additional fees are required, please also  
charge our Deposit Account No. 111833.

Respectfully submitted,

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